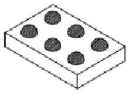
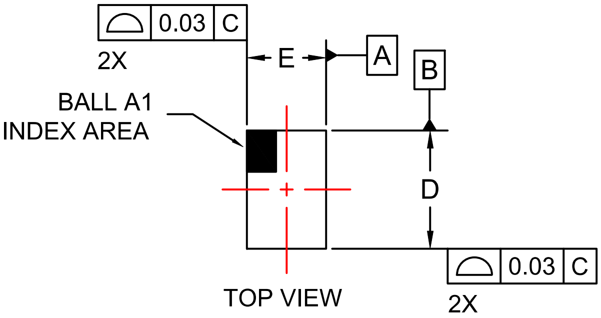
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

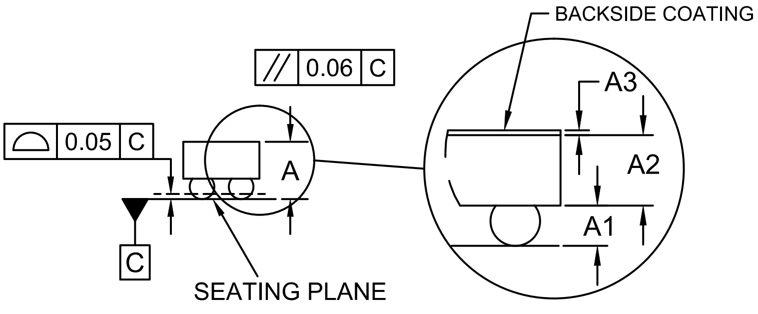


WLCSP6 1.36x0.76x0.581
CASE 567XQ
ISSUE O

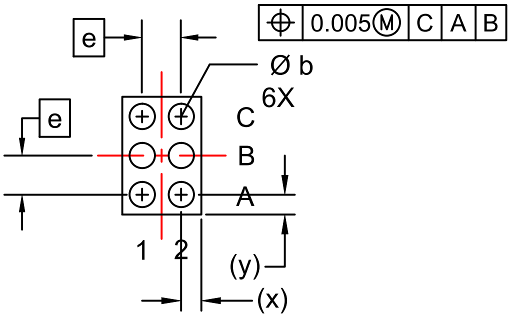
DATE 03 APR 2019



TOP VIEW



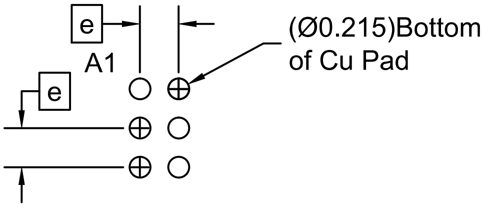
SIDE VIEW



BOTTOM VIEW

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.540	0.581	0.622
A1	0.183	0.203	0.223
A2	0.335	0.353	0.371
A3	0.022	0.025	0.028
b	0.240	0.260	0.280
D	1.33	1.36	1.39
E	0.73	0.76	0.79
e	0.40 BSC		
x	0.150	0.165	0.180
y	0.250	0.265	0.280



RECOMMENDED MOUNTING FOOTPRINT*
(NSMD PAD TYPE)

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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DESCRIPTION:	**WLCSP6 1.36x0.76x0.581**	**PAGE 1 OF 1**